

# MN74HC245/MN74HC245S

## Octal TRI-STATE Transceivers

### Outline

The MN74HC245/MN74HC245S consists of high speed non-inverting bidirectional buffers having eight 3-state outputs for bidirectional asynchronous transmission of the inputs through a data bus line.

Because of the large current outputs, these buffers assure high speed operation even when driving a large capacity bus line. They have an input  $\bar{G}$  to enable the outputs when the level is "L", and a direction control input DIR. When the level of the DIR input is "H", data is transmitted from the input A to the output B, and when the level of the DIR input is "L", data is transmitted from the input B to the output A.

Owing to the silicon gate CMOS process, these buffers have realized low power consumption and high noise immunity equivalent to those of a standard CMOS and the operation speed as high as of an LS TTL, and can directly drive fifteen LS TTL inputs.

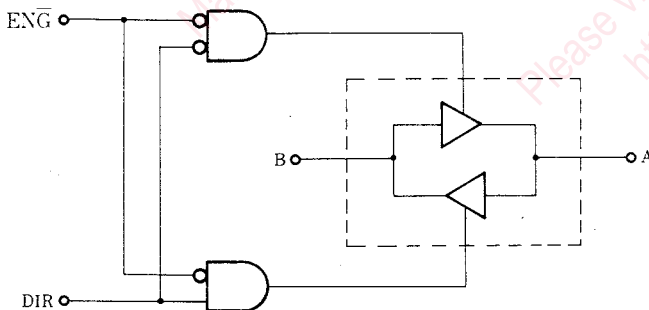
To protect the input and output against electrostatic breakdown, a resistor and a diode are used for the  $V_{CC}$  and the GND. The pin configuration and the function are the same as those of the standard 54LS/74LS logic family.

### Truth Table

Enable $\bar{G}$	Direction Control DIR	Operation
L	L	B data to A bus
L	H	A data to B bus
H	×	Hi-Z

Note 1. Hiz : High impedance  
2. × : "H" or "L" either will do.

### Logic Diagram

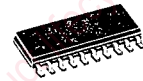


P-5



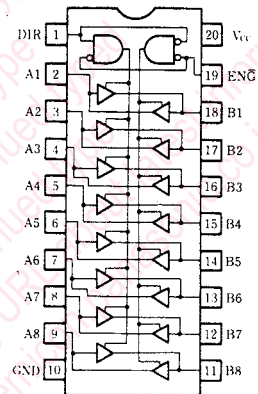
20-pin plastic DIL package

P-6



20-pin PANAFLAT package (SO-20D)

### Pin Configuration



### ■ Absolute Maximum Ratings

Item		Symbol	Rating	Unit	
Supply voltage		$V_{CC}$	-0.5~+7.0	V	
Input output voltage		$V_I, V_O$	-0.5~ $V_{CC}+0.5$	V	
Input protective diode current		$I_{IK}$	±20	mA	
Output parasitic diode current		$I_{OK}$	±20	mA	
Output current		$I_O$	±35	mA	
Supply current		$I_{CC}, I_{GND}$	±70	mA	
Storage temperature		$T_{stg}$	-65~+150	°C	
Power dissipation	MN74HC245	$T_a = -40 \sim +60^\circ\text{C}$	$P_D$	400 Decrease to 200mW at the rate of 8mW/°C	mW
		$T_a = +60 \sim +85^\circ\text{C}$			
	MN74HC245S	$T_a = -40 \sim +60^\circ\text{C}$	$P_D$	275 Decrease to 200mW at the rate of 3.8mW/°C	mW
		$T_a = +60 \sim +85^\circ\text{C}$			

### ■ Recommended Operating Conditions

Item	Symbol	$V_{CC}(V)$	Rating	Unit
Operating power supply voltage	$V_{CC}$		1.4~6.0	V
Input output voltage	$V_I, V_O$		0~ $V_{CC}$	V
Operating temperature	$T_A$		-40~+85	°C
Input rise, fall time	$t_r, t_f$	2.0	0~1000	ns
		4.5	0~500	ns
		6.0	0~400	ns

### ■ DC Characteristics (GND=0V)

Item	Symbol	$V_{CC}$ (V)	Test Condition			Temperature					Unit
			$V_I$	$V_O$	Unit	$T_a = 25^\circ\text{C}$			$T_a = -40 \sim +85^\circ\text{C}$		
						min.	typ.	max.	min.	max.	
Input voltage high level	$V_{IH}$	2.0				1.5			1.5		V
		4.5				3.15			3.15		
		6.0				4.2			4.2		
Input voltage low level	$V_{IL}$	2.0						0.3		0.3	V
		4.5						0.9		0.9	
		6.0						1.2		1.2	
Output voltage high level	$V_{OH}$	2.0	$V_{IH}$	-20.0	μA	1.9	2.0		1.9		V
		4.5	$V_{IH}$	-20.0	μA	4.4	4.5		4.4		
		6.0	or	-20.0	μA	5.9	6.0		5.9		
		4.5	$V_{IL}$	-6.0	mA	3.92			3.84		
		6.0	$V_{IL}$	-7.8	mA	5.48			5.34		
Output voltage low level	$V_{OL}$	2.0	$V_{IH}$	20.0	μA		0.0	0.1		0.1	V
		4.5	$V_{IH}$	20.0	μA		0.0	0.1		0.1	
		6.0	or	20.0	μA		0.0	0.1		0.1	
		4.5	$V_{IL}$	6.0	mA			0.26		0.33	
		6.0	$V_{IL}$	7.8	mA			0.26		0.33	
Input leakage current	$I_I$	6.0	$V_I = V_{CC}$ or GND					±0.1		±1.0	μA
3-state output OFF leakage current	$I_{OZ}$	6.0	$V_I = V_{IH}$ or $V_{IL}$ $V_O = V_{CC}$ or GND					±0.5		±5.0	μA
Static supply current	$I_{CC}$	6.0	$V_I = V_{CC}$ or GND, $I_O = 0$					8.0		80.0	μA

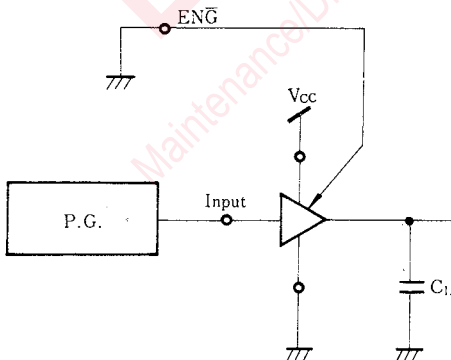
■ AC Characteristics (GND=0V, Input transition time ≤ 6ns, C<sub>L</sub> = 50pF)

Item	Symbol	V <sub>CC</sub> (V)	Test Condition	Temperature					Unit
				Ta=25°C			Ta=-40~+85°C		
				min.	typ.	max.	min.	max.	
Output rise time	t <sub>TLH</sub>	2.0			25	75		95	ns
		4.5		8	15	19			
		6.0		7	13	16			
Output fall time	t <sub>THL</sub>	2.0			20	75		95	ns
		4.5		7	15	19			
		6.0		6	13	16			
Propagation time (L→H)	t <sub>PLH</sub>	2.0			18	75		95	ns
		4.5		8	15	19			
		6.0		7	13	16			
Propagation time (H→L)	t <sub>PHL</sub>	2.0			20	75		95	ns
		4.5		8	15	19			
		6.0		6	13	16			
3-state propagation time (H→Z)	t <sub>PHZ</sub>	2.0	R <sub>L</sub> =1kΩ		24	150		190	ns
		4.5		15	30	38			
		6.0		13	26	33			
3-state propagation time (L→Z)	t <sub>PLZ</sub>	2.0	R <sub>L</sub> =1kΩ		29	150		190	ns
		4.5		17	30	38			
		6.0		14	26	33			
3-state propagation time (Z→H)	t <sub>PZH</sub>	2.0	R <sub>L</sub> =1kΩ		28	100		125	ns
		4.5		12	20	25			
		6.0		9	17	21			
3-state propagation time (Z→L)	t <sub>PZL</sub>	2.0	R <sub>L</sub> =1kΩ		37	125		155	ns
		4.5		14	25	31			
		6.0		11	21	26			

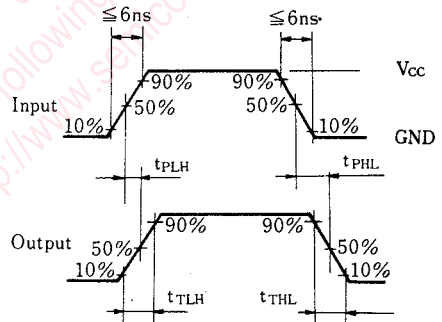
• Switching time measuring circuit and waveforms

(1) t<sub>TLH</sub>, t<sub>THL</sub>, t<sub>PLH</sub>, t<sub>PHL</sub>

1. Measuring circuit



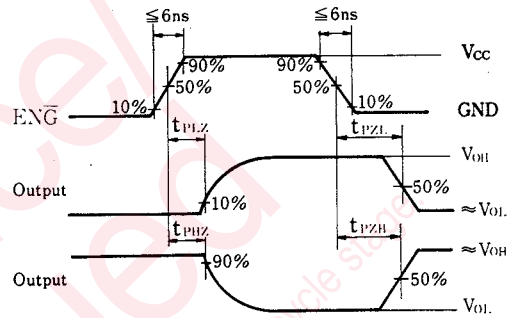
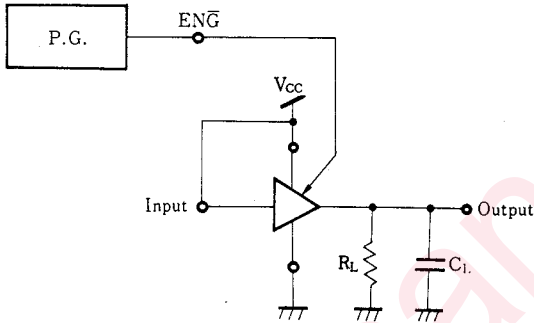
2. Switching waveforms



(2)  $t_{PHZ}$ ,  $t_{PZH}$

1. Measuring circuit

2. Switching waveforms

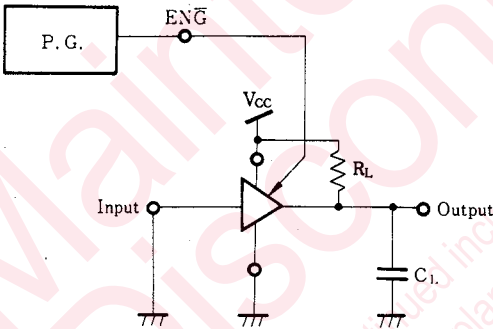


(3)  $t_{PLZ}$ ,  $t_{PZL}$

1. Measuring circuit

2. Switching waveforms

See above (2) 2 for waveforms.



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